

Board File Name: Design Name.		blufi_poe.PcbDoc btWifi_poe	
Hole Count:		894	
Via Count:		841	
Pad Count:		1034	
Board Material:		FR408	
Number of Layers:		4	
Copper Weight:		1 Oz	
Finished Board Thickness:		0.8 mm	
Min Trace:		5mil	
Min Space:		4mil	
Soldermask type:		LPI BLUE	
Pad finish:		ENIG	
Silkscreen Color:		WHITE	
Minimum Via Size:		Drill	Dia
		10mil	20mil
Files:			
Top Layer:		GTL	
Top Soldermask:		GTS	
Top Paste:		GTP	
Top Silkscreen:		GTO	
Signal 1		G1	
Signal 2		G2	
Bottom Layer:		GBL	
Bottom Soldermask:		GBS	
Bottom Paste:		GBP	
Bottom Silkscreen:		GBO	
Board Outline:		GM1cut according to this layer	
Drill:		TXT	Top-Bottom
Documentation:		PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,40mil	3,5	
1	Top Layer		1,40mil		
	Dielectric1				
	Signal Layer 1	FR408	5,10mil	3,65	
2			1,40mil		
	Dielectric 3				
	Signal Layer 2	FR408	18,00mil	4,03	
3			1,40mil		
	Dielectric 2				
	Signal Layer 2	FR408	5,10mil	3,65	
4			1,40mil		
	Bottom Layer				
	Bottom Solder	Solder Resist	0,40mil	3,5	
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Silkscreen Color: WHITE	
Minimum Via Size:	Drill 10mil Dia 20mil
Files:	
Top Layer: GTL	
Top Soldermask: GTS	
Top Paste: GTP	
Top Silkscreen: GTO	
Signal 1: G1	
Signal 2: G2	
Bottom Layer: GBL	
Bottom Soldermask: GBS	
Bottom Paste: GBP	
Bottom Silkscreen: GBO	
Board Outline: GM1cut according to this layer	
Drill: TXT Top-Bottom	
Documentation: PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric3				
	Signal Layer 2	FR408	16.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



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Bottom Layer: GBL	
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Bottom Paste: GBP	
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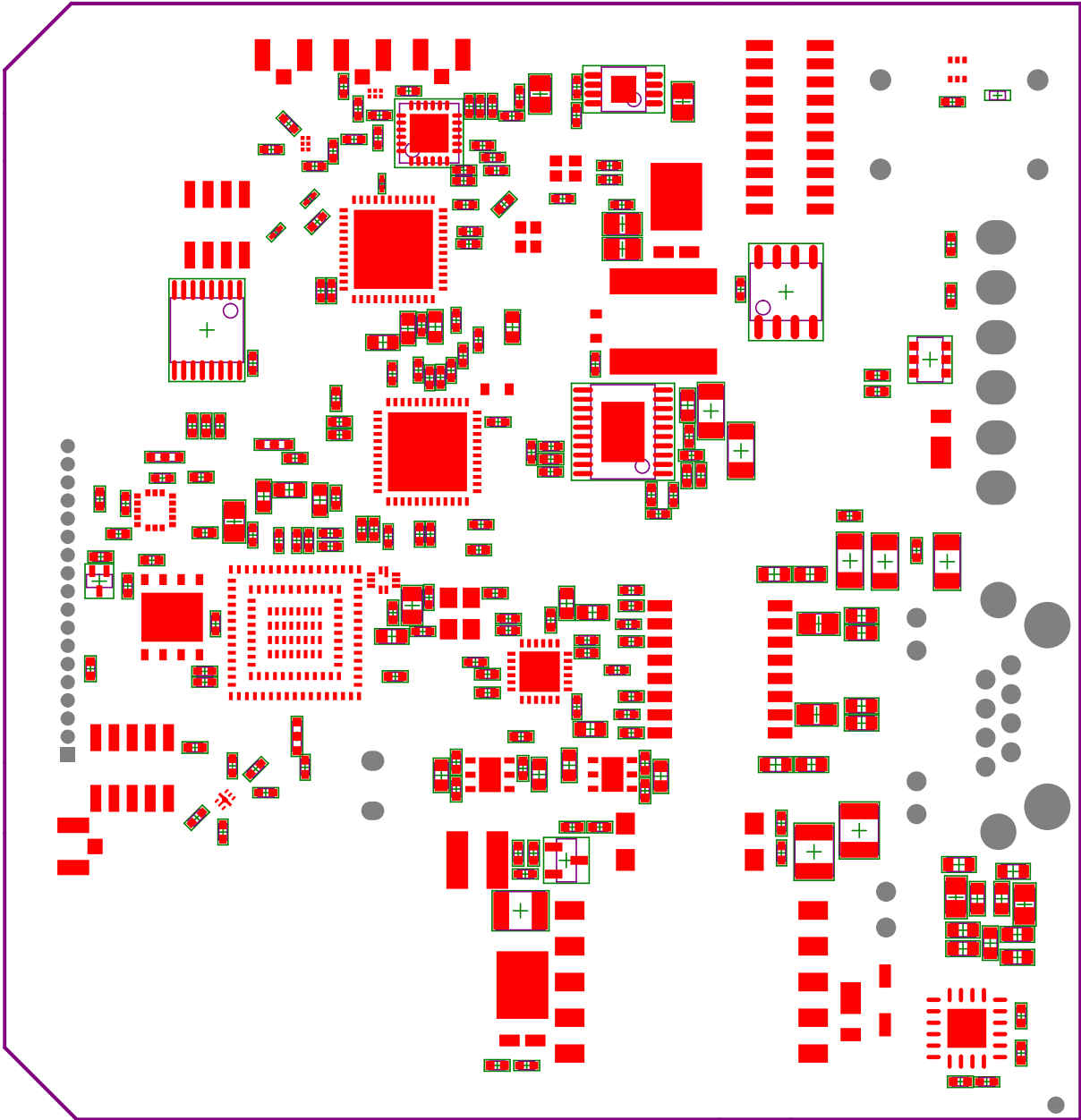
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric1				
	Signal Layer 1	FR408	16.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric2				
	Signal Layer 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
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Top Layer: GTL	
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Signal 1: G1	
Signal 2: G2	
Bottom Layer: GBL	
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Bottom Paste: GBP	
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	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric3				
	Signal Layer 2	FR408	16.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



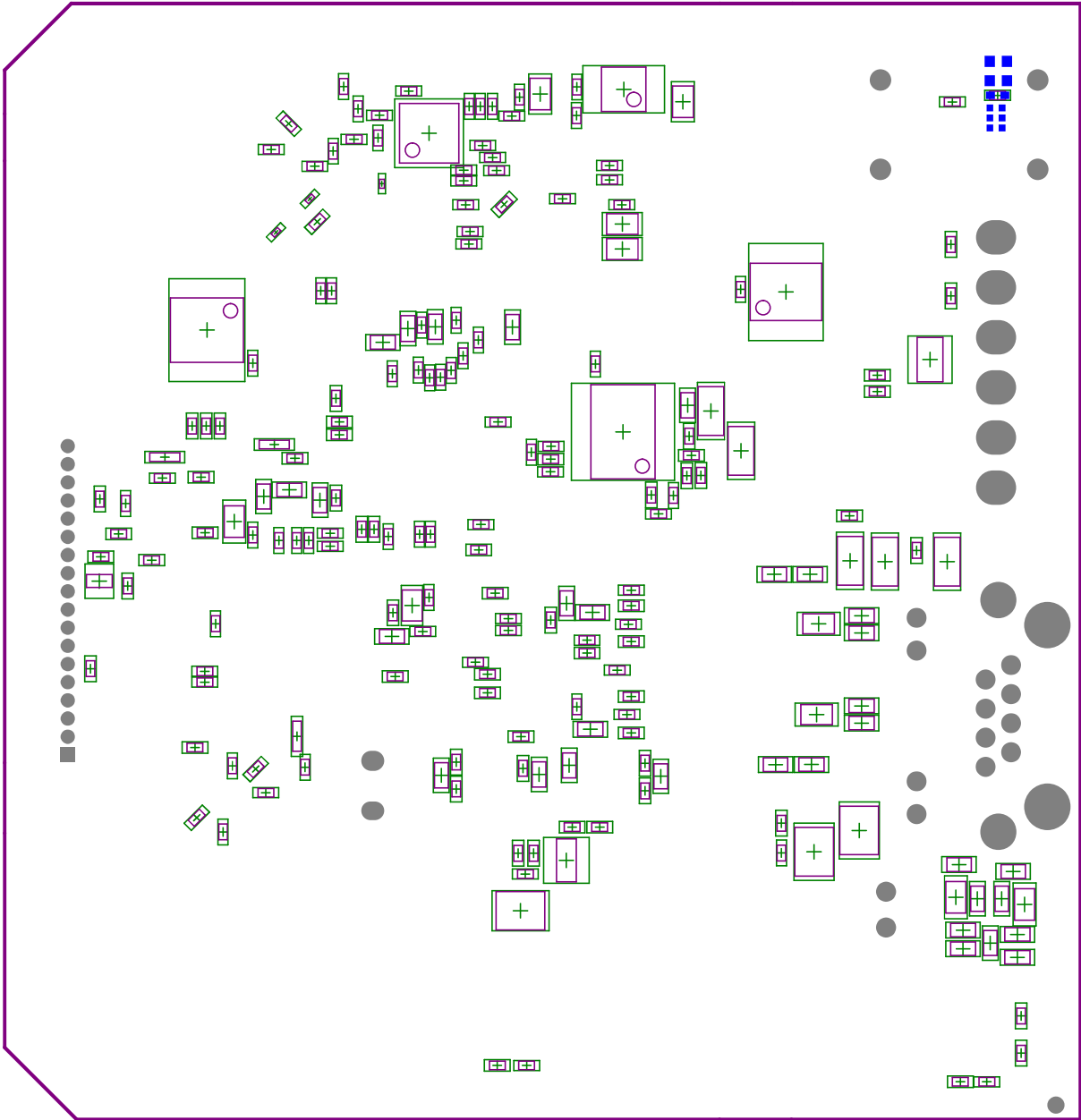


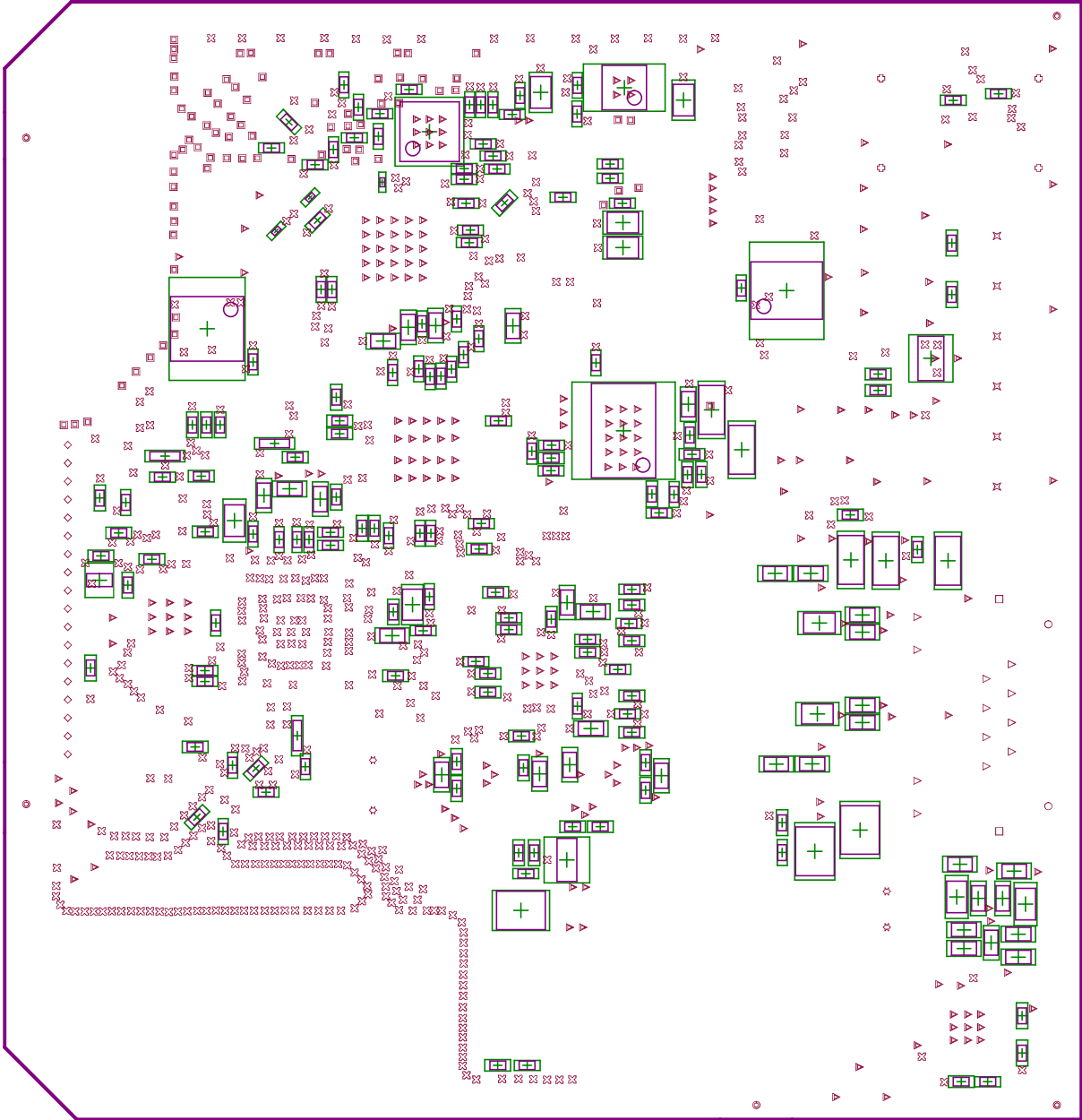
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Files:	
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Top Paste: GTP	
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1	Top Layer		1.40mil		
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	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric 3	FR408	16.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2	FR408	5.10mil	3.65	
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Top Soldermask: GTP	
Top Paste: GTO	
Top Silkscreen: G1	
Signal 1: G2	
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	Dielectric 2	FR408	5.10mil	3.65	
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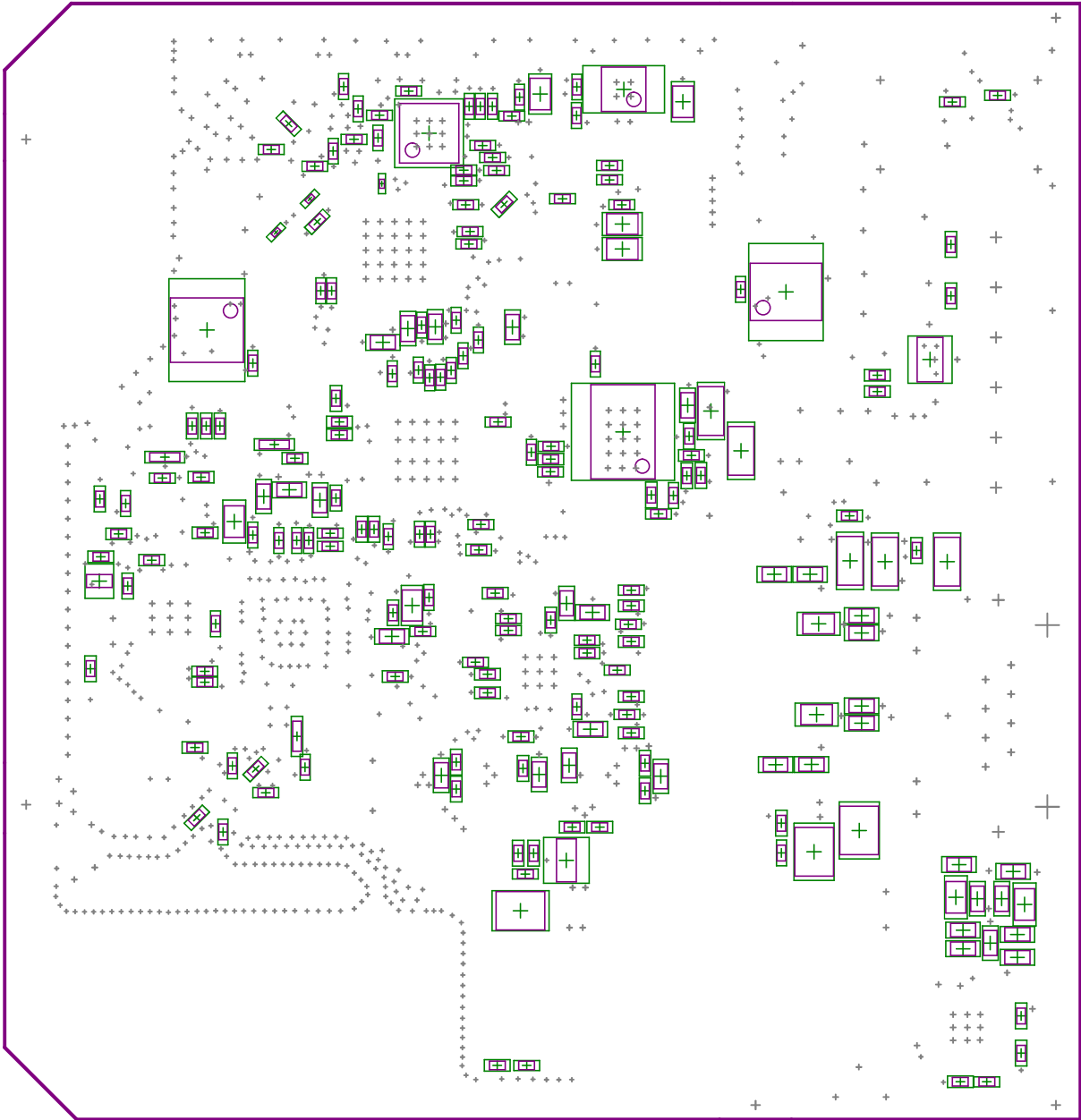
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	Dielectric 3	FR408	16.00mil	4.03		
3	Signal Layer 2		1.40mil			
	Dielectric 2	FR408	5.10mil	3.65		
4	Bottom Layer		1.40mil			
	Bottom Solder	Solder Resist	0.40mil	3.5		
	Bottom Overlay					
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
⊗	550	0.254mm	PTH	Round	Top Layer - Bottom Layer	Via
⬢	75	0.325mm	PTH	Round	Top Layer - Bottom Layer	Via
▶	216	0.356mm	PTH	Round	Top Layer - Bottom Layer	Via
◆	18	0.600mm	PTH	Round	Top Layer - Bottom Layer	Pad
⊕	4	0.700mm	PTH	Round	Top Layer - Bottom Layer	Pad
▼	12	0.889mm	PTH	Round	Top Layer - Bottom Layer	Pad
⊗	4	1.000mm	PTH	Round	Top Layer - Bottom Layer	Pad
⊕	5	1.200mm	NPTH	Round	Top Layer - Bottom Layer	Pad
⬢	6	1.500mm	PTH	Round	Top Layer - Bottom Layer	Pad
⬢	2	1.575mm	PTH	Round	Top Layer - Bottom Layer	Pad
⬢	2	3.257mm	PTH	Round	Top Layer - Bottom Layer	Pad
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	Dielectric3				
	Signal Layer 2	FR408	18.00mil	4.03	
3	Dielectric 2				
	Bottom Layer	FR408	5.10mil	3.65	
4	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				